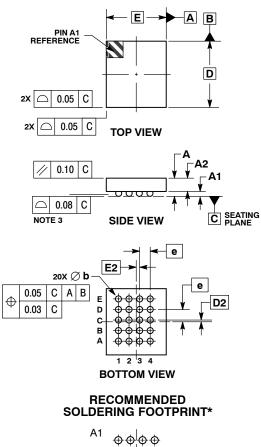
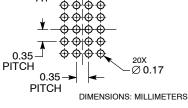




SCALE 4:1





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

CROWING OF SOLDER I			
	MILLIMETERS		
DIM	MIN	MAX	
Α		0.65	
A1	0.13	0.19	
A2	0.38 REF		
b	0.17	0.23	
D	2.187 BSC		
D2	0.058 BSC		
Е	1.987 BSC		
E2	0.112 BSC		
е	0.35 BSC		

GENERIC **MARKING DIAGRAM***

XXXXX XXXXX ALYW .

- А = Assembly Location
- = Wafer Lot L
- Υ = Year
- = Work Week W
- = Pb-Free Package .

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

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